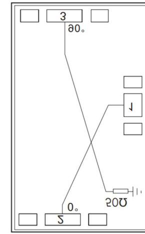
Performance

- Frequency: 22~32GHz
- Insertion loss: 1.5dB
- Chip size: 1.95*0.8*0.1mm

Function Diagram

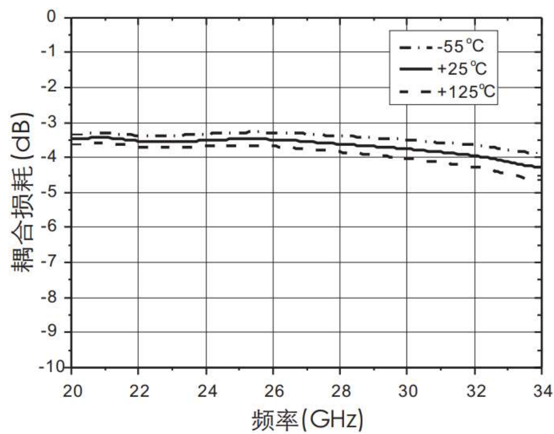


Electrical Specifications (Ta=+25℃, 50Ω system)

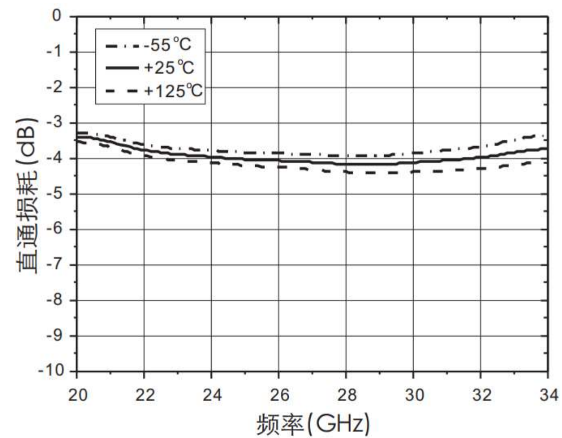
Parameter	Min	Typical	Max	Unit
Frequency Range	22~32			GHz
Insertion Loss	-	1.5	-	dB
Input Return loss	20	21	-	dB
Output Return loss	17	20	-	dB
Isolation	19	20	-	dB
Amplitude Balance	-	±0.5	-	dB
Phase Balance	-	±2	-	Deg

Test Curves (Die chip + Bonding line test)

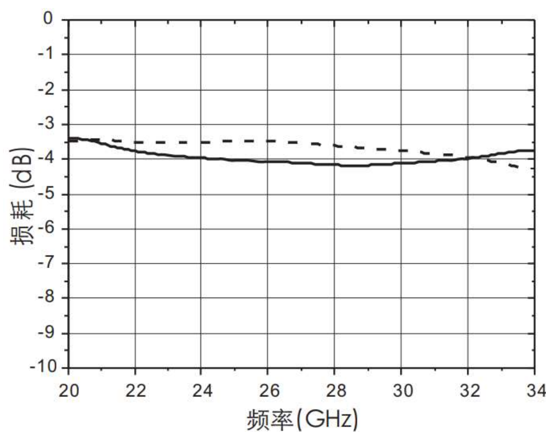
Insertion loss vs. Freq



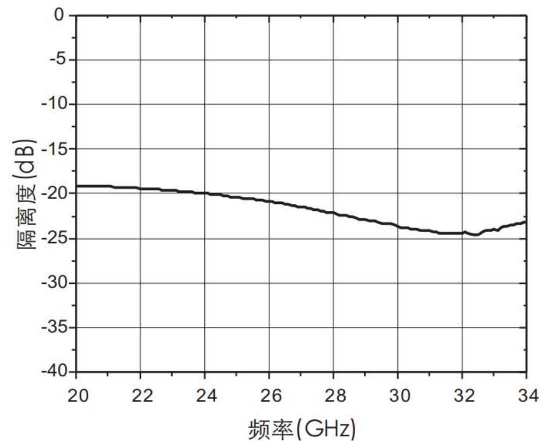
Insertion loss vs. Freq

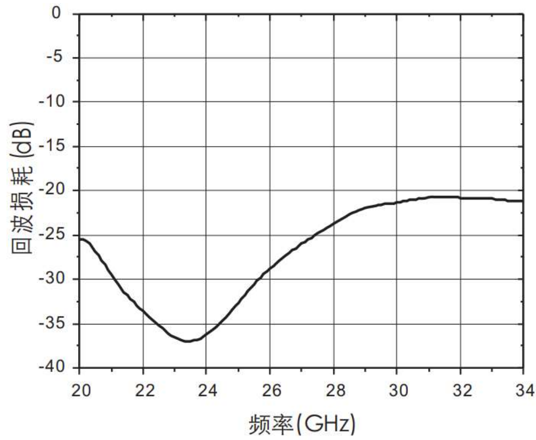


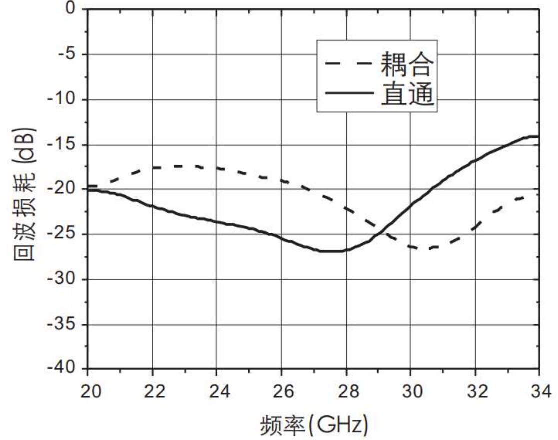
Insertion loss vs. Freq

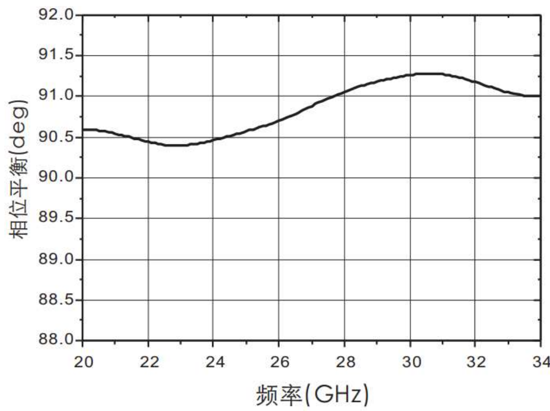


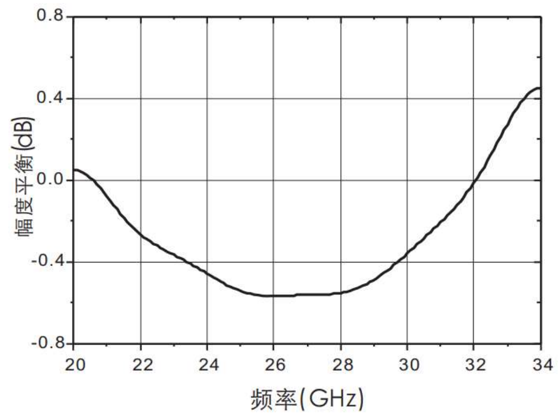
Isolation vs. Freq



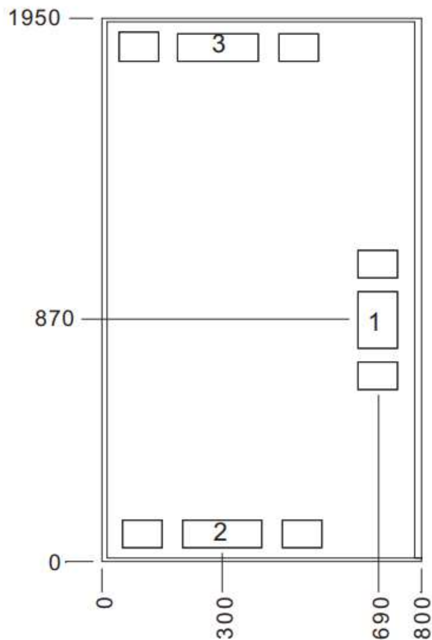








Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, size: 100*200(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFC	Coupling output port
3	RFOUT	Thru output port
-	GND	Bottom must be grounded

Absolute Max Ratings

Max Input Power	+33dBm
Static Class	Class 1B
Storage Temperature	-65 ~ +150℃
Operating Temperature	-55 ~ +125℃

Note: For high power application, assemble with Eutectic sintering.

Application